



BSI Standards Publication

Electronic components — Long-term storage of electronic semiconductor devices

Part 5: Die and wafer devices

National foreword

This British Standard is the UK implementation of EN 62435-5:2017. It is identical to IEC 62435-5:2017.

The UK participation in its preparation was entrusted to Technical Committee EPL/47, Semiconductors.

A list of organizations represented on this committee can be obtained on request to its secretary.

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Published by BSI Standards Limited 2017

ISBN 978 0 580 83550 6

ICS 31.020

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This Published Document was published under the authority of the Standards Policy and Strategy Committee on 30 April 2017.

Amendments/corrigenda issued since publication

Date	Text affected
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ICS 31.020

English Version

Electronic components - Long-term storage of electronic semiconductor devices - Part 5: Die and wafer devices (IEC 62435-5:2017)

Composants électroniques - Stockage de longue durée des dispositifs électroniques à semiconducteurs -
Partie 5: Dispositifs de puces et plaquettes
(IEC 62435-5:2017)

Elektronische Bauteile - Langzeitlagerung elektronischer Halbleiterbauelemente - Teil 5: Chip- und Wafererzeugnisse
(IEC 62435-5:2017)

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European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

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European foreword

The text of document 47/2328/FDIS, future edition 1 of IEC 62435-5, prepared by IEC/TC 47 "Semiconductor devices" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 62435-5:2017.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2017-11-24
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2020-02-24

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IEC 60068-2-17	NOTE	Harmonized as EN 60068-2-17.
IEC 60068-2-20	NOTE	Harmonized as EN 60068-2-20.
IEC 60749-3	NOTE	Harmonized as EN 60749-3.
IEC 60749-20-1	NOTE	Harmonized as EN 60749-20-1.
IEC 60749-21	NOTE	Harmonized as EN 60749-21.
IEC 60749-22	NOTE	Harmonized as EN 60749-22.
IEC 61340-5-1	NOTE	Harmonized as EN 61340-5-1.
IEC 61340-2-1	NOTE	Harmonized as EN 61340-2-1.
IEC/TR 62258-3	NOTE	Harmonized as CLC/TR 62258-3.
IEC 62435-1	NOTE	Harmonized as EN 62435-1.

Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 When an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 62435-2	-	Electronic components - Long-term storage of electronic semiconductor devices - Part 2: Deterioration mechanisms	EN 62435-2	-

CONTENTS

FOREWORD.....	4
INTRODUCTION.....	6
1 Scope.....	8
2 Normative references	8
3 Terms, definitions and abbreviated terms	8
3.1 Terms and definitions.....	8
3.2 Abbreviations	9
4 Storage requirements	9
4.1 General.....	9
4.2 Assembly data	9
4.3 Prerequisite for storage.....	9
4.4 Damage to die products during long-term storage	9
4.5 Mechanical storage conditions	10
4.6 Long-term storage environment	10
4.7 Recommended inert atmosphere purity	11
4.8 Chemical contamination	11
4.9 Vacuum packing	11
4.9.1 General	11
4.9.2 Vacuum dry pack.....	11
4.10 Positive pressure systems for packing	11
4.11 Use of packing material having sacrificial properties	11
4.12 Use of bio-degradable material	12
4.13 Plasma cleaning	12
4.14 Electrical effects	12
4.15 Protection from radiation.....	12
4.16 Periodic qualification of stored die products	12
5 Long-term storage failure mechanisms	13
6 LTS concerns, method, verification and limitations	13
6.1 General.....	13
6.2 Wafers.....	13
6.3 Bare dice	14
7 Deterioration mechanisms specific to bare die and wafers	15
7.1 Wire bondability	15
7.2 Staining	15
7.3 Topside delamination.....	16
8 Specific handling concerns	16
8.1 Die on wafer film frames	16
8.2 Devices and dice embossed or punched tape storage	16
8.3 Handling damage.....	16
Annex A (informative) Audit checklist.....	17
Bibliography.....	20

Table 1 – LTS exposure concerns for wafers	14
Table 2 – LTS exposure concerns for bare dice	15
Table A.1 – Planning checklist	17

INTERNATIONAL ELECTROTECHNICAL COMMISSION

**ELECTRONIC COMPONENTS – LONG-TERM STORAGE
OF ELECTRONIC SEMICONDUCTOR DEVICES –****Part 5: Die and wafer devices**

FOREWORD

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International Standard IEC 62435-5 has been prepared by IEC technical committee 47: Semiconductor devices.

The text of this standard is based on the following documents:

FDIS	Report on voting
47/2328/FDIS	47/2351/RVD

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 62435 series, published under the general title *Electronic components – Long-term storage of electronic semiconductor devices*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

INTRODUCTION

This document applies to the long-duration storage of electronic components.

This is a document for long-term storage (LTS) of electronic devices drawing on the best long-term storage practices currently known. For the purposes of this document, LTS is defined as any device storage whose duration may be more than 12 months for product scheduled for long duration storage. While intended to address the storage of unpackaged semiconductors and packaged electronic devices, nothing in this document precludes the storage of other items under the storage levels defined herein.

Although it has always existed to some extent, obsolescence of electronic components and particularly of integrated circuits, has become increasingly intense over the last few years.

Indeed, with the existing technological boom, the commercial life of a component has become very short compared with the life of industrial equipment such as that encountered in the aeronautical field, the railway industry or the energy sector.

The many solutions enabling obsolescence to be resolved are now identified. However, selecting one of these solutions should be preceded by a case-by-case technical and economic feasibility study, depending on whether storage is envisaged for field service or production, for example:

- remedial storage as soon as components are no longer marketed;
- preventive storage anticipating declaration of obsolescence.

Taking into account the expected life of some installations, sometimes covering several decades, the qualification times, and the unavailability costs, which can also be very high, the solution to be adopted to resolve obsolescence should often be rapidly implemented. This is why the solution retained in most cases consists in systematically storing components which are in the process of becoming obsolescent.

The technical risks of this solution are, a priori, fairly low. However, it requires perfect mastery of the implemented process and especially of the storage environment, although this mastery becomes critical when it comes to long-term storage.

All handling, protection, storage and test operations are recommended to be performed according to the state of the art.

The application of the approach proposed in this standard in no way guarantees that the stored components are in perfect operating condition at the end of this storage. It only comprises a means of minimizing potential and probable degradation factors.

Some electronic device users have the need to store electronic devices for long periods of time. Lifetime buys are commonly made to support production runs of assemblies that will exceed the production timeframe of its individual parts. This puts the user in a situation requiring careful and adequate storage of such parts to maintain the as-received solderability and minimize any degradation effects to the part over time. Major degradation concerns are moisture, electrostatic fields, ultra-violet light, large variations in temperature, air-borne contaminants, and outgassing.

Warranties and sparring also present a challenge for the user or repair agency as some systems have been designated to be used for long periods of time, in some cases for up to 40 years or more. Some of the devices needed for repair of these systems will not be available from the original supplier for the lifetime of the system or the spare assembly may be built with the original production run but then require long-term storage. This document was developed to provide a standard for storing electronic devices for long periods of time.

For storage of devices that are moisture sensitive but that do not need to be stored for long periods of time, refer to IEC TR 62258-3.

Long-term storage assumes that the device is going to be placed in uninterrupted storage for a number of years. It is essential that it is useable after storage. Particular attention should be paid to storage media surrounding the devices together with the local environment.

These guidelines do not imply any warranty of product or guarantee of operation beyond the storage time given by the original device manufacturer.

The IEC 62435 series is intended to ensure that adequate reliability is achieved for devices in user applications after long-term storage. Users are encouraged to request data from suppliers to these specifications to demonstrate a successful storage life as requested by the user. These standards are not intended to address built-in failure mechanisms that would take place regardless of storage conditions.

These standards are intended to give practical guide to methods of long-term storage of electronic components where this is intentional or planned storage of product for a number of years. Storage regimes for work-in-progress production are managed according to company internal process requirements and are not detailed in this series of standards.

The IEC 62345 series includes a number of parts. Parts 1 to 4 apply to any long-term storage and contain general requirements and guidance, whereas Parts 5 to 9¹ are specific to the type of product being stored. It is intended that the product specific part should be read alongside the general requirements of Parts 1 to 4.

Electronic components requiring different storage conditions are covered separately starting with Part 5.

The structure of the IEC 62435 series as currently conceived is as follows:

Part 1 – General

Part 2 – Deterioration mechanisms

Part 3 – Data

Part 4 – Storage

Part 5 – Die and wafer devices

Part 6 – Packaged or finished devices

Part 7 – MEMS

Part 8 – Passive electronic devices

Part 9 – Special cases

¹ Under preparation.

ELECTRONIC COMPONENTS – LONG-TERM STORAGE OF ELECTRONIC SEMICONDUCTOR DEVICES –

Part 5: Die and wafer devices

1 Scope

This part of IEC 62435, is applicable to long-term storage of die and wafer devices and establishes specific storage regimen and conditions for singulated bare die and partial or complete wafers of die including die with added structures such as redistribution layers and solder balls or bumps or other metallisation. This part also provides guidelines for special requirements and primary packaging that contain the die or wafers for handling purposes. Typically, this part is used in conjunction with IEC 62435-1 for long-term storage of devices whose duration can be more than 12 months for products scheduled for long duration storage.

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 62435-2, *Electronic components – long-term storage of electronic semiconductor devices – Part 2: Deterioration mechanisms*

3 Terms, definitions and abbreviated terms

For the purposes of this document, the following terms, definitions and abbreviated terms apply.

ISO and IEC maintain terminological databases for use in standardization at the following addresses:

- IEC Electropedia: available at <http://www.electropedia.org/>
- ISO Online browsing platform: available at <http://www.iso.org/obp>

3.1 Terms and definitions

3.1.1

storage environment

specially controlled storage area, with particular control of temperature, humidity, atmosphere and any other conditions depending on the product requirements

3.1.2

long-term storage

LTS

planned storage of components to extend the life-cycle for a duration with the intention of supporting future use

3.1.3

desiccant

hygroscopic substance used to remove moisture from an atmosphere